

IN THE SPECIFICATION:

Please replace the third paragraph on page 3 with the following rewritten paragraph:

Dice having bond pads, i.e. on the active surface, complicate the construction of multi-chip modules, particularly when wire-bonding is the connection method of choice. As taught in United States Patent 5,012,323 of Farnworth, United States Patents 5,422,435, 5,495,398 and 5,502,289 of Takiar et al., and United States Patent 5,600,183 of Gates, Jr., bonding with wire or other ~~conductor~~ conductors necessitates that the stacked dice be of progressively smaller size.

Please replace the third paragraph on page 6 with the following rewritten paragraph:

FIG. 11 is a perspective top view of another embodiment of a high density IC module of the ~~invention~~; invention.

Please replace the paragraph bridging page 6 and 7 with the following rewritten paragraph:

The substrate 20 is shown with elongate through-slots 30A and 30B, each through-slot passing through the substrate between the first side 16 and the second side 18. The through-slots 30A, 30B are configured to provide access from the opposite side 18 of the substrate 20 for wire-bonding the bond pads 22 to connection sites 32 of a conductor ~~pattern 34~~ pattern 34A, 34B on the substrate. The dice 12A and 12B are spaced a distance 36 apart, leaving room for the through-slot 30C therebetween.